

## CLAIMS

1. A module for an optical device being provided with a solid-state image sensor having an effective pixel region formed on one side thereof and an optical path demarcating unit for demarcating an optical path from an objective lens to said effective pixel region, comprising:

a translucent cover placed opposite to said effective pixel region on said solid-state image sensor;

a bonding portion for fixedly bonding said translucent cover to said solid-state image sensor; and

a joint portion for fixedly joining said optical path demarcating unit to said translucent cover;

whereby said objective lens is positioned with respect to said effective pixel region with the one side of said solid-state image sensor defined as a positioning reference, by fixedly joining said optical path demarcating unit to said translucent cover via said joint portion, and by fixedly bonding said translucent cover to said solid-state image sensor via said bonding portion.

2. The module for an optical device as set forth in claim 1, wherein said joint portion is joined by fixedly bonding said translucent cover and said optical path demarcating unit.

3. The module for an optical device as set forth in claim 2, wherein said translucent cover is formed to have a plane size smaller than the plane size of the one side of said solid-state image sensor.

4. The module for an optical device as set forth in claim 3, wherein said bonding portion contains a photosensitive bonding agent.

5. The module for an optical device as set forth in claim 4, wherein a space is formed between said effective pixel region and said translucent cover, and  
said bonding portion is formed at the peripheral portion of said effective pixel region on the one side of said solid-state image sensor.

6. The module for an optical device as set forth in claim 5, wherein said bonding portion is configured to seal said space formed between said effective pixel region and said translucent cover.

7. The module for an optical device as set forth in claim 6, wherein said lens is placed so as to oppose to said effective pixel region, and is held by said optical path demarcating unit.

8. The module for an optical device as set forth in claim 7, wherein an image processing device is bonded to a wiring substrate, and said solid-state image sensor is bonded to a plane portion of said image processing device.

9. The module for an optical device as set forth in claim 8, being used as a module for a camera.

10. A manufacturing method of a module for an optical device being provided with a solid-state image sensor having an effective pixel region formed on one side thereof, and an optical path demarcating unit for demarcating an optical path to said effective pixel region, comprising steps of placing a translucent cover so as to oppose to said effective pixel region;

bonding said translucent cover to said solid-state image sensor; and joining said optical path demarcating unit to said translucent cover.

11. The manufacturing method of a module for an optical device as set forth in claim 10, wherein the step of joining said optical path demarcating unit to said translucent cover is executed by bonding said translucent cover and said optical path demarcating unit.

12. The manufacturing method of a module for an optical device as set forth in claim 11, wherein a photosensitive bonding agent is used for bonding said solid-state image sensor and said translucent cover.

13. The manufacturing method of a module for an optical device as set forth in claim 12, wherein bonding of said solid-state image sensor and said translucent cover is executed by patterning said photosensitive bonding agent at the peripheral portion of said effective pixel region on the one side of said solid-state image sensor.

14. The manufacturing method of a module for an optical device as set forth in claim 13, further comprising a step of bonding said solid-state image sensor to a plane portion of an image processing device bonded to a wiring substrate.

15. The manufacturing method of a module for an optical device as set forth in claim 14, wherein said module for an optical device is used as a module for a camera.